Product End-of-Life Disassembly Instructions

Product Category: Personal Computers	
Marketing Name / Model **[List multiple models if applicable.]**	
HP ProDesk 600 G5 SFF Business PC	

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPI products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking, please contact HP's Sustainability Contact.

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	7
Batteries, excluding Li-Ion batteries.	All types including standard alkaline, coin or button style batteries	1
Li-Ion batteries. Include all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, RTC coin cell, etc.)	Battery(ies) are attached to the product by (*check all that apply with an* "x" *inside the* "[ ]"): [ ] screws [ ] snaps [ ] adhesive [ ] other. Explain _____ NOTE: Add detailed removal procedures including required tools in the sections 3.1 and 3.2.	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords	DC Cable for External Power Supply	1
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs		0

Last revalidation date 09-May-2018

Item Description	Notes	Quantity of items included in product
already listed as a separate item above)		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

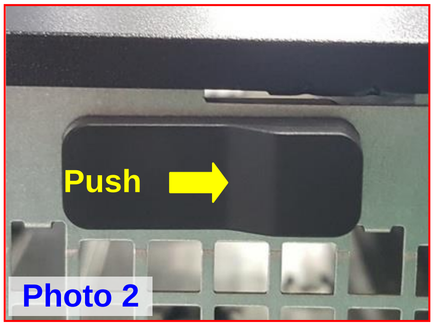
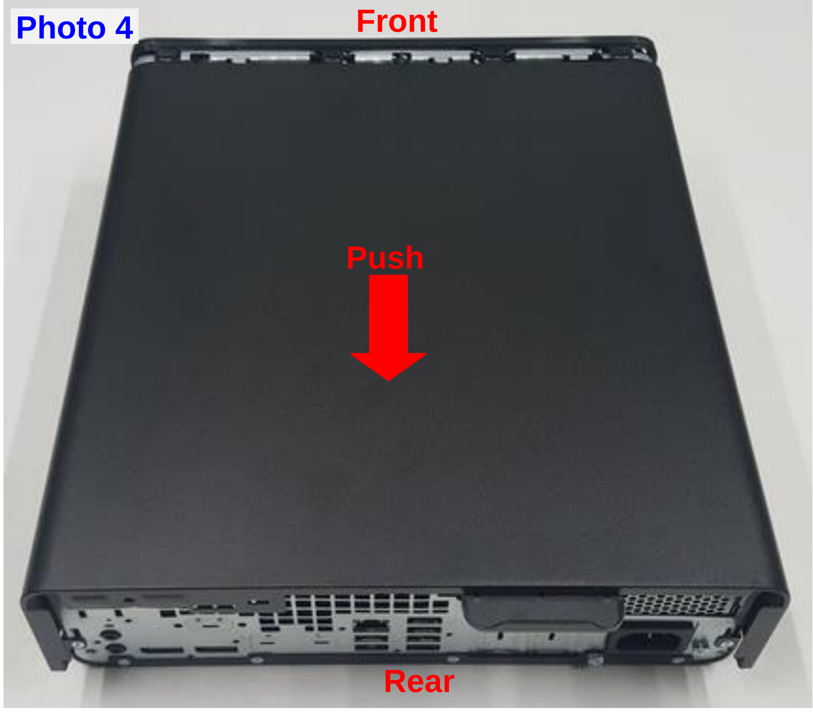
Tool Description	Tool Size (if applicable)
Star screwdriver	OD 3.3mm
Cross screwdrive	OD 3.0mm
Cross screwdrive	OD 6.0mm

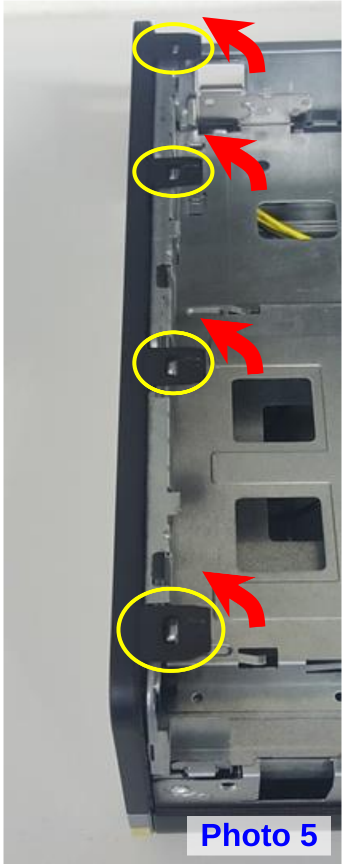
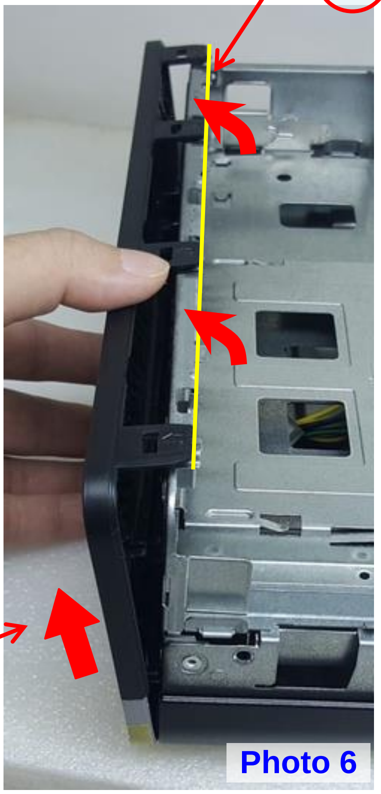
3.0 Product Disassembly Process

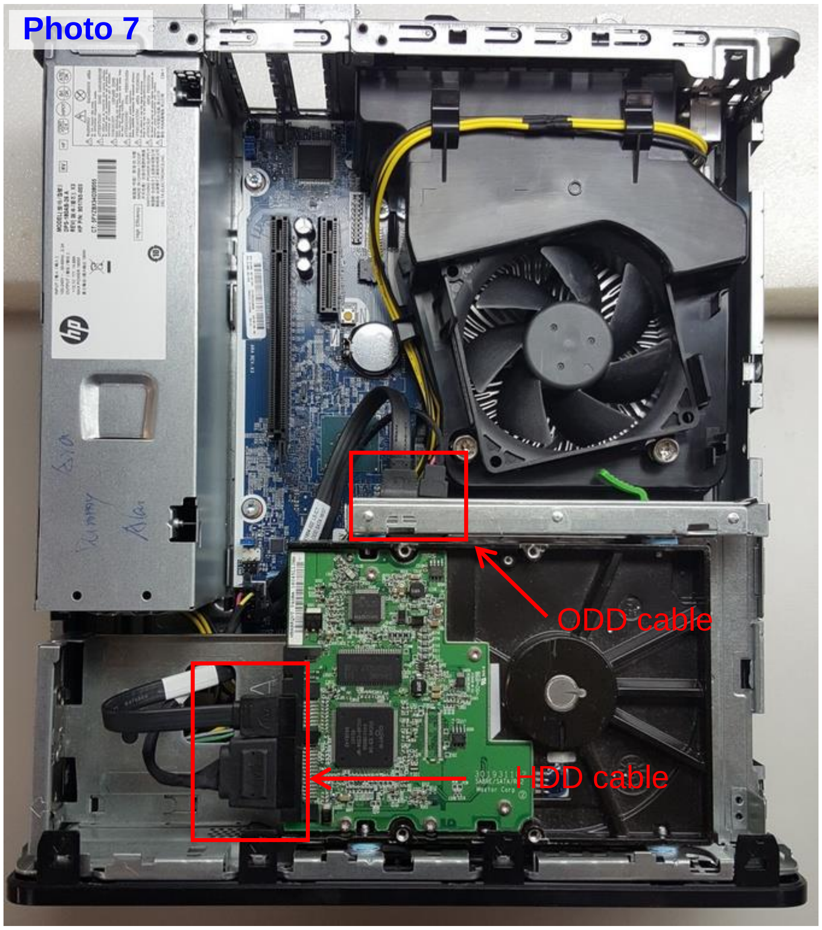
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure:

1. Remove side panel
2. Remove front bezel
3. Unplug ODD & HDD cables
4. Remove drive cage
5. Remove FIO cage
6. Remove ODD & HDD
7. Remove all cables
8. Remove fan duct
9. Remove cooler
10. Remove CPU
11. Remove Memory
12. Remove WLAN module
13. Remove SSD module
14. Remove all PCIEXP cards
15. Remove 2nd serial card
16. Remove option card
17. Remove card reader
18. Remove antenna cable
19. Remove MB and battery
20. Remove PSU
21. Remove speaker

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

1 Push thumb latch on the chassis rear side. Push side panel in the end as shown, and then pick up from chassis as shown. **See photo 1, 2, 3, 4**	   

2 Release 4 bezel latches from chassis by pulling outwards the bezel latches then as shown. **See Photo 5** Pick up bezel in the order as shown. **See Photo 6**	 **Photo 5**  Rotate bezel until the bezel latches align this line. ① ② Lift up bezel away from chassis **Photo 6**

3 Unplug ODD & HDD cables as shown. **See Photo 7**	

4 Press HDD cage first then push button as shown.

See Photo 8

Rotation drive cage then pass through HDD cables to drive cage then remove drive cage as shown.

See Photo 9, 10

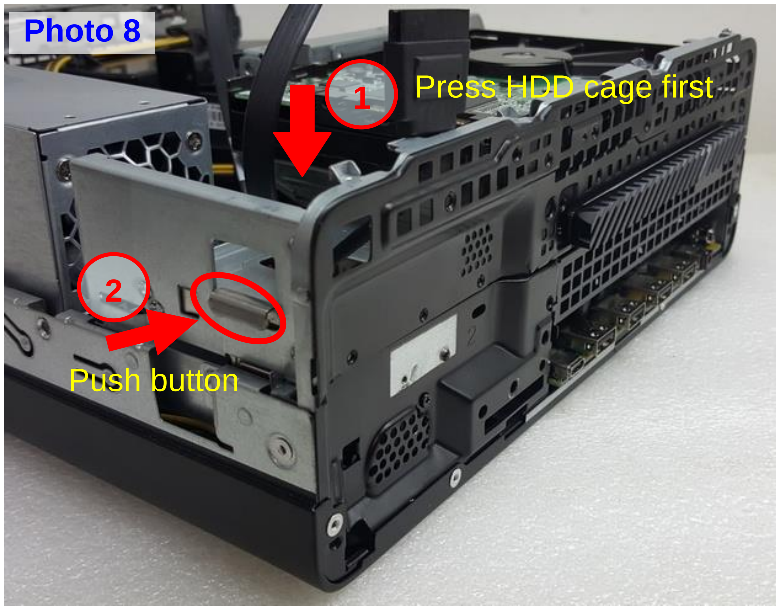


Photo 8

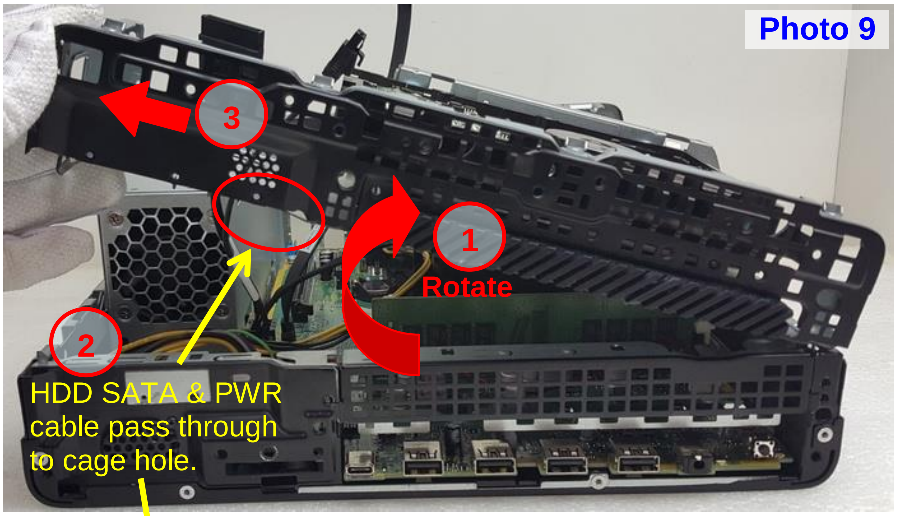


Photo 9

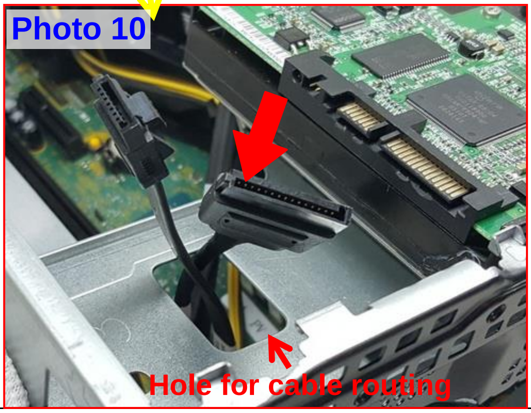


Photo 10

5 Pick up FIO bracket from chassis as shown.

See Photo 11

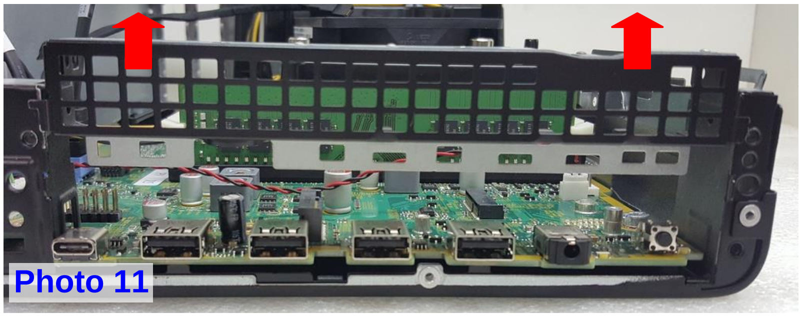


Photo 11

6 Push HDD latch then push HDD in the order and release screws as shown.

See Photo 12, 13

Screw tool:
Star screwdriver OD 3.3mm.

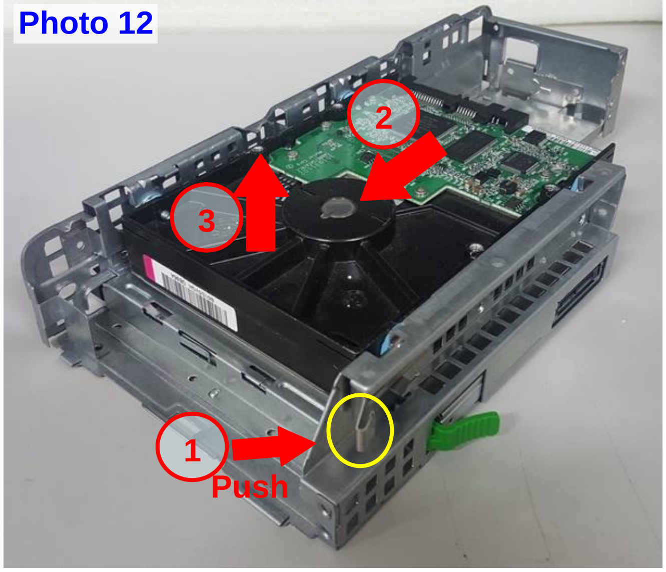
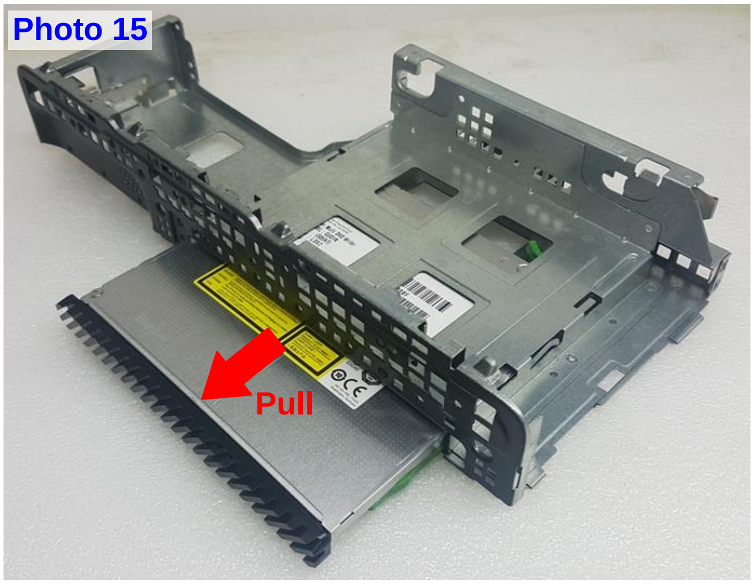


Photo 12

Photo 13

Push ODD latch then pull ODD as shown. **See Photo 14, 15**	**Photo 14**  **Photo 15** 

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HPI instructions for this template are available at EL-MF877-01

7 Release all cables

See Photo 16, 17, 18, 19, 20

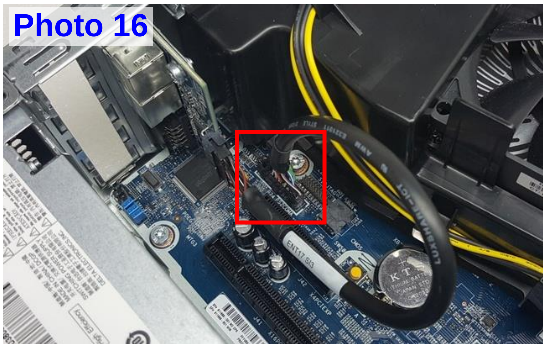


Photo 16

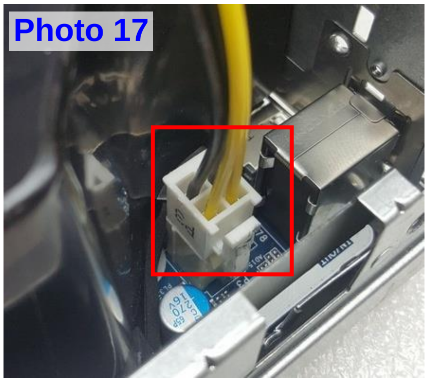


Photo 17

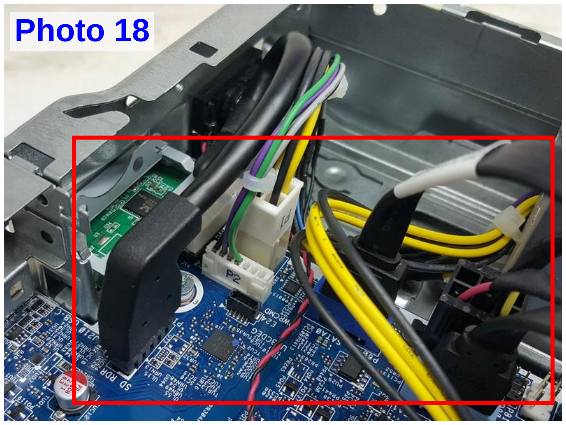


Photo 18

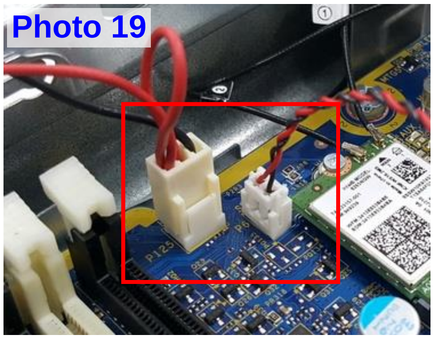


Photo 19

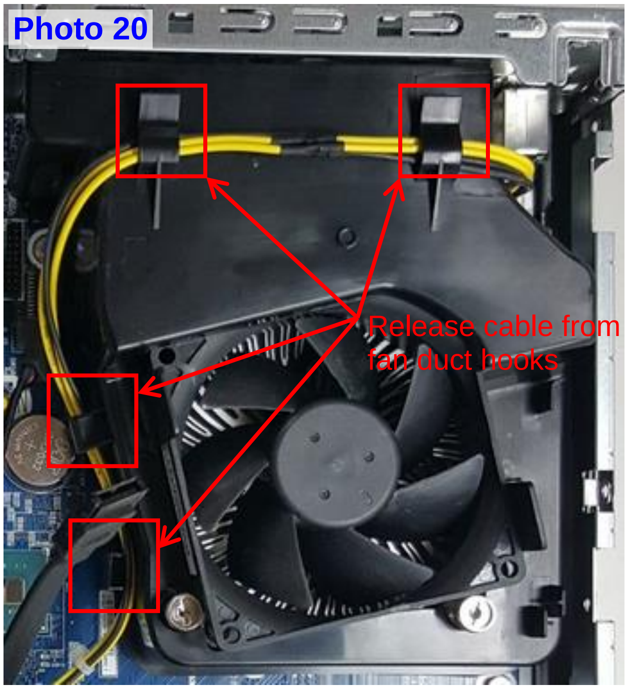
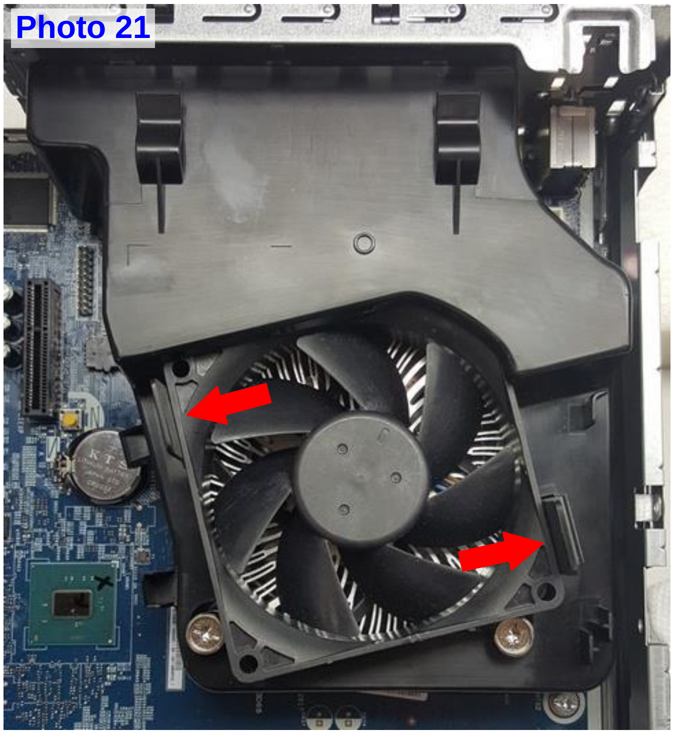
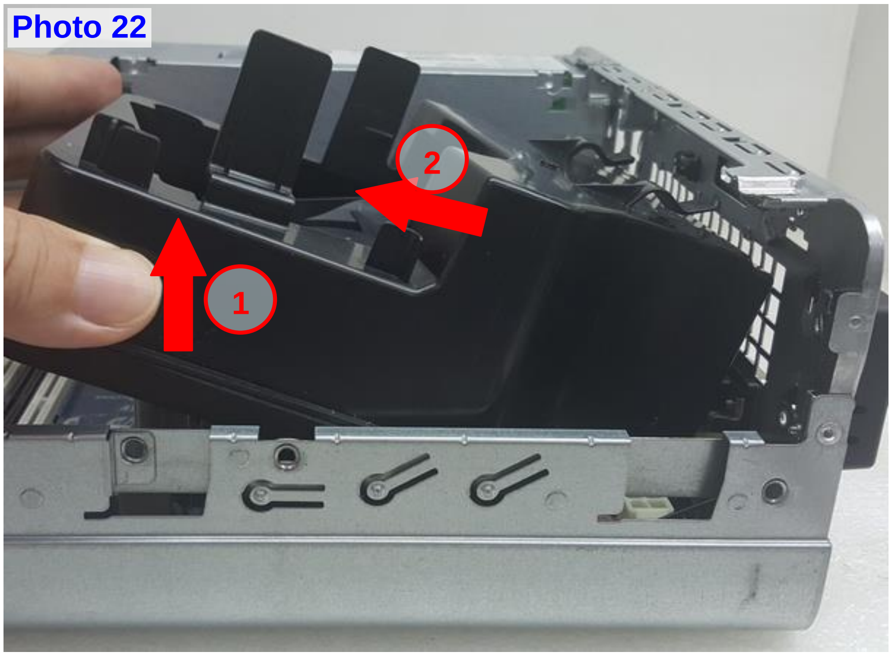


Photo 20

Release cable from fan duct hooks

8 Push fan duct latch then pick up fan duct from chassis as shown. **See Photo 21, 22**	Photo 21  Photo 22 

9 Release 4 screws from cooler then unplug cable as shown.

See Photo 23, 24

Screw tool:
Star screwdriver OD 3.3mm.

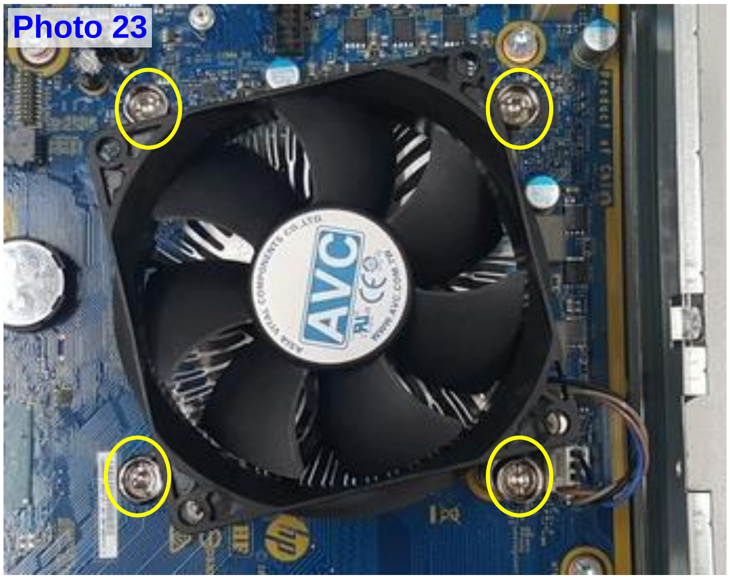


Photo 23

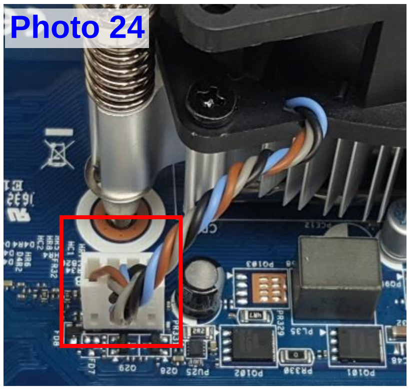
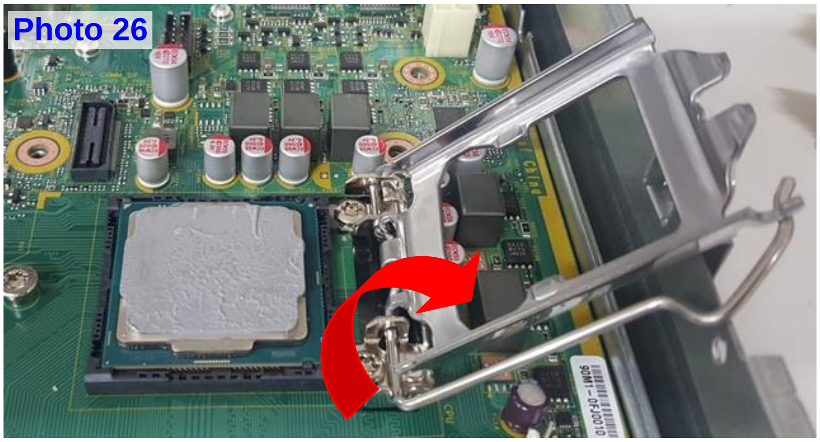


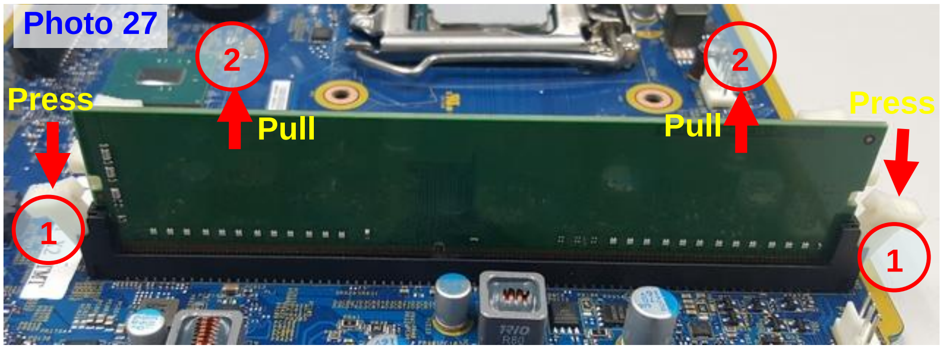
Photo 24

10 Unlock CPU socket latch and open cover then pick up CPU as shown. **See Photo 25, 26**	 Photo 25  Photo 26

11 Press memory slot levers by pulling outward.

Then pull up memory as shown.

See Photo 27



12 Release WLAN card screw then pull up WLAN card from MB as shown.

See Photo 28, 29

Screw tool:
Cross screwdriver OD 3.0mm.

13 Release SSD card screw then pull up SSD card from MB as shown.

See Photo 30, 31

Screw tool:
Cross screwdriver OD 3.0mm.

Photo 30

Photo 31

14 Open slot lock cover then pull up all PCIEXP cards as shown.

See Photo 32, 33

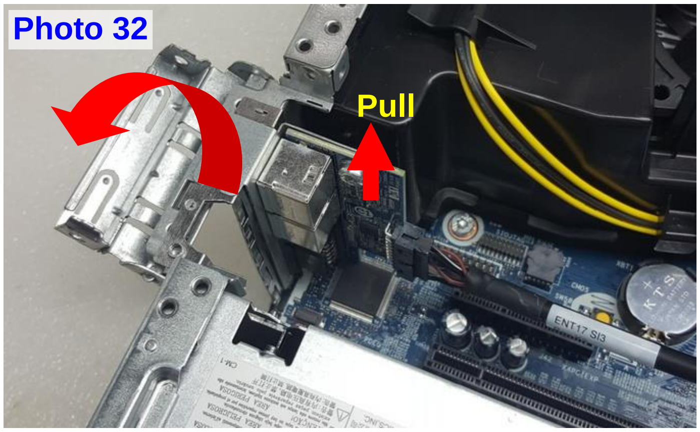


Photo 32

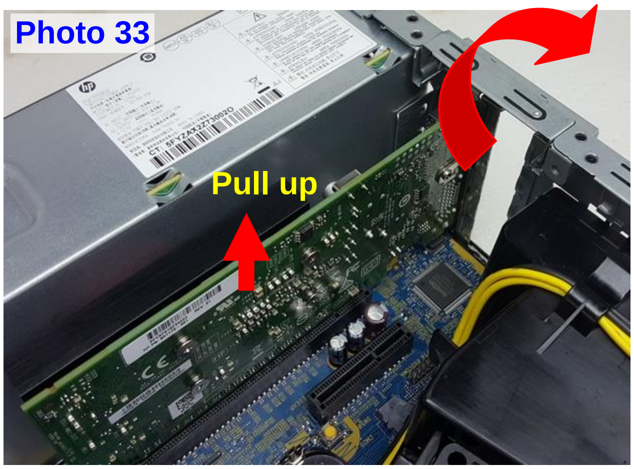


Photo 33

15 Unplug 2nd serial card cable then release two screws then release 2nd serial card as shown.

See Photo 34, 35, 36

Screw tool: Hexagon socket wrench 4.6mm

Photo 34

Photo 35

Photo 36

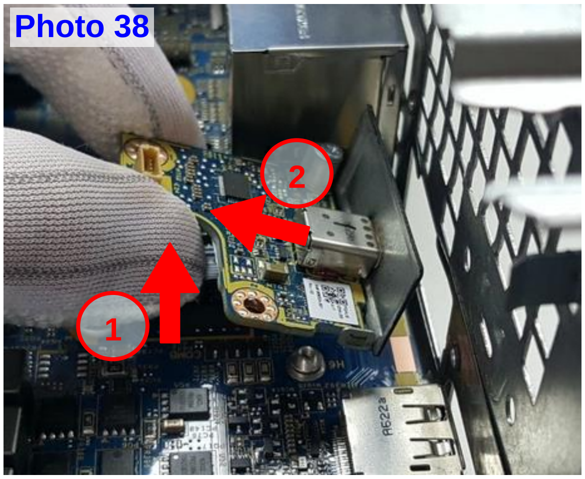
16 Release two screws then pull up option card as shown.

See Photo 37, 38

Screw tool:
Cross screwdriver OD 3.0mm.

Photo 37

Photo 38



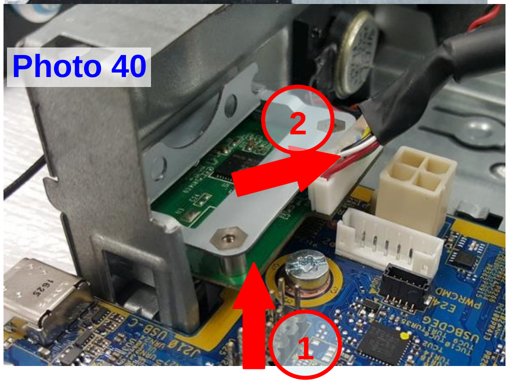
17 Release one screw then pull up card reader as shown.

See Photo 39, 40

Screw tool:
Star screwdriver OD 3.3mm.

Photo 39

Photo 40



18 Release front antenna screw then pull up antenna cable.

Press rear antenna cover latch then pull up cover from chassis.

Release rear antenna screw then pull up antenna cable.

See Photo 41, 42, 43, 44, 45

Screw tool:
Cross screwdriver OD 3.0mm.

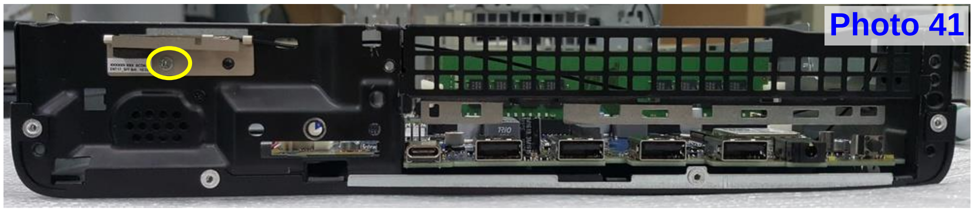


Photo 41

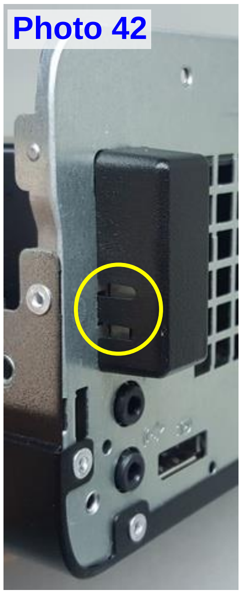


Photo 42

Photo 43

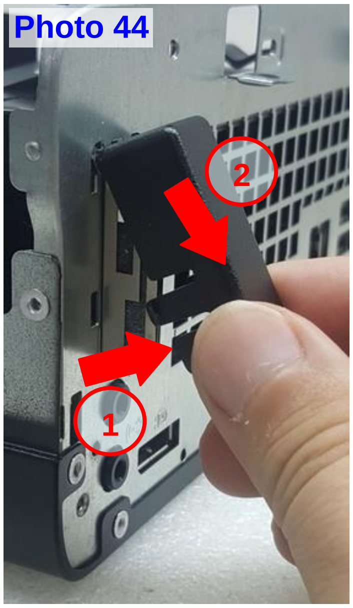


Photo 44

Photo 45

19 Release betty and 8 screws then pick up MB to release from chassis in the order as shown.

See Photo 46, 47

Screw tool:
Star screwdriver OD 3.3mm.

Photo 46

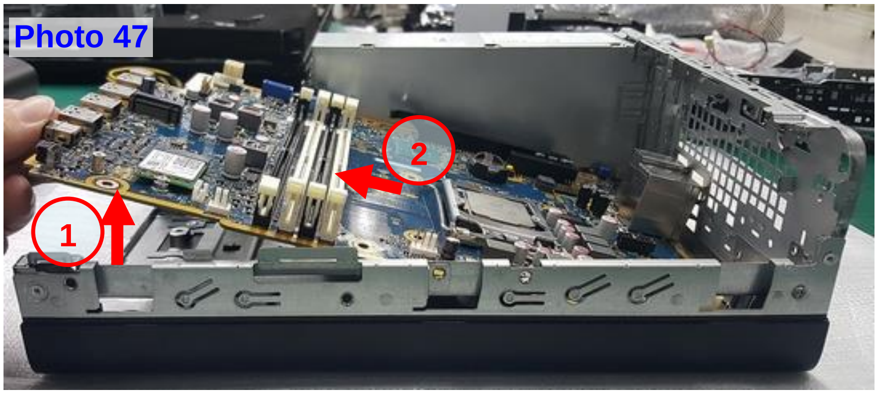


Photo 47

20 Release 4 screws as shown.

Push PSU latch then pull PSU then pick up PSU from chassis as shown.

See Photo 48, 49, 50

Screw tool:
Star screwdriver OD 3.3mm.


Photo 48

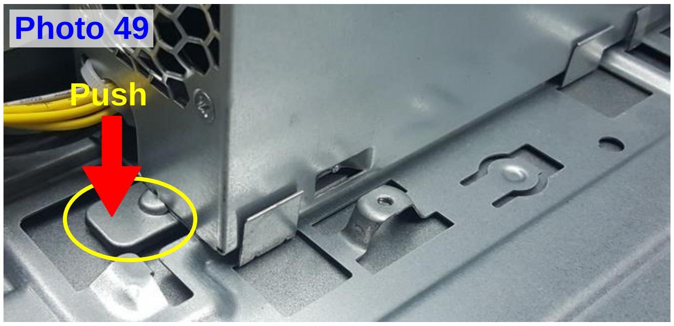


Photo 49

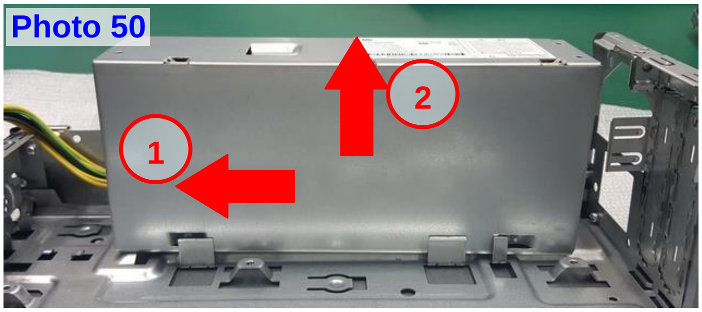


Photo 50

21 Release one screw then pick up speaker from chassis as shown.

See Photos 51, 52

Screw tool:
Cross screwdriver OD 3.0mm.

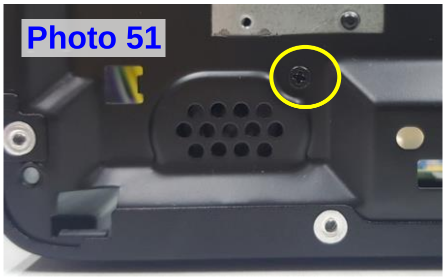


Photo 51

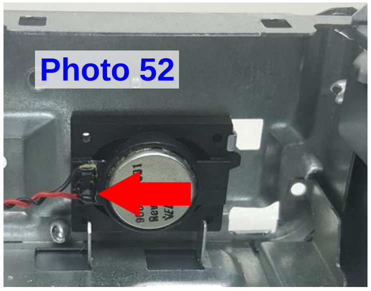


Photo 52